

L Number	Hits	Search Text	DB	Time stamp
189	16	257/666.ccls. and electrodeposition	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:28
190	12	(257/666.ccls. and electrodeposition) and (@ad<20010418)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:46
191	33	leadless and electrodeposition	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:32
192	24	(leadless and electrodeposition) and (@ad<20010418)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:29
193	7	438/15.ccls. and electrodeposition	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:33
194	9	438/64.ccls. and electrodeposition	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:34
195	0	438/25.ccls. and electrodeposition	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:34
196	8	438/123.ccls. and electrodeposition	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:43
197	1	("3783499").PN.	USPAT	2004/04/15 21:38
198	7	438/124.ccls. and electrodeposition	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:50
199	2	438/55.ccls. and electrodeposition	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:44
200	2	438/51.ccls. and electrodeposition	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:45
201	1466	(leadframe or (lead adj frame)) and (electrodeposition or bath)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:46
202	1440	((leadframe or (lead adj frame)) and (electrodeposition or bath)) and (leads or lead)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:46

203	9	"L2020" and (@ad<20010418)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:46
204	1440	((leadframe or (lead adj frame)) and (electrodeposition or bath)) and (leads or lead)) and (leads or lead)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:46
205	1131	((leadframe or (lead adj frame)) and (electrodeposition or bath)) and (leads or lead)) and (@ad<20010418)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:47
206	45	((leadframe or (lead adj frame)) and (electrodeposition or bath)) and (leads or lead)) and (@ad<20010418)) and leadless	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:47
-	370	electrodeposition same frame	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 18:31
-	309	(electrodeposition same frame) and (@ad<20010418)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:25
-	97	((electrodeposition same frame) and (@ad<20010418)) and (chip or die or ic or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 21:24